

# **N0600N**

## MOS FIELD EFFECT TRANSISTOR

R07DS0220EJ0100 Rev.1.00 Jan 25, 2011

## **Description**

The N0600N is N-channel MOS Field Effect Transistor designed for high current switching applications.

### **Features**

- Low on-state resistance
  - $R_{DS(on)1} = 25 \text{ m}\Omega \text{ MAX.} (V_{GS} = 10 \text{ V}, I_D = 15 \text{ A})$
  - ---  $R_{DS(on)2}$  = 36 mΩ MAX. ( $V_{GS}$  = 4.5 V,  $I_D$  = 15 A)
- Low input capacitance
  - $C_{iss}$  = 1380 pF TYP. ( $V_{DS}$  = 10 V,  $V_{GS}$  = 0 V)

## **Ordering Information**

Part No.	Lead Plating	Packing	Package
N0600N-S17-AY *1	Pure Sn (Tin)	Tube	Isolated TO-220
		50p/tube	typ. 2.2 g

Note: \*1. Pb-free (This product does not contain Pb in the external electrode and other parts.)

## Absolute Maximum Ratings $(T_A = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V <sub>GS</sub> = 0 V)	$V_{DSS}$	60	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	$V_{GSS}$	±20	V
Drain Current (DC)	I <sub>D(DC)</sub>	±30	Α
Drain Current (pulse) *1	I <sub>D(pulse)</sub>	±60	Α
Total Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>T1</sub>	20	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	2.0	W
Channel Temperature	T <sub>ch</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Single Avalanche Current *2	I <sub>AS</sub>	9.2	Α
Single Avalanche Energy *2	E <sub>AS</sub>	12.5	mJ

#### **Thermal Resistance**

Channel to Case (Drain) Thermal Resistance  $R_{th(ch-C)}$  6.25 °C/W Channel to Ambient Thermal Resistance \*2  $R_{th(ch-A)}$  62.5 °C/W

Notes: \*1. PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

\*2. Starting  $T_{ch}$  = 25°C,  $R_G$  = 25  $\Omega$ ,  $V_{DD}$  = 30 V,  $V_{GS}$  = 20  $\rightarrow$  0 V

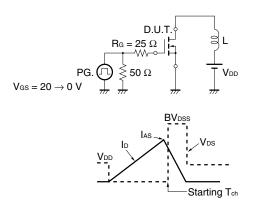
## Electrical Characteristics (T<sub>A</sub> = 25°C)

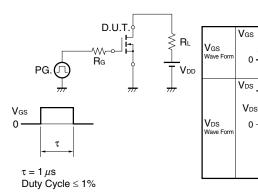
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$
Gate Leakage Current	I <sub>GSS</sub>			±100	nA	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to Source Cut-off Voltage	$V_{GS(off)}$	1.5	2.0	2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward Transfer Admittance *1	y <sub>fs</sub>	4			S	$V_{DS} = 10 \text{ V}, I_{D} = 15 \text{ A}$
Drain to Source On-state	R <sub>DS(on)1</sub>		17.5	25	mΩ	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$
Resistance *1	R <sub>DS(on)2</sub>		22.3	36	mΩ	$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$
Input Capacitance	C <sub>iss</sub>		1380		pF	V <sub>DS</sub> = 10 V,
Output Capacitance	Coss		186		pF	$V_{GS} = 0 V$ ,
Reverse Transfer Capacitance	C <sub>rss</sub>		109		pF	f = 1 MHz
Turn-on Delay Time	t <sub>d(on)</sub>		5.7		ns	$V_{DD} = 30 \text{ V}, I_D = 15 \text{ A},$
Rise Time	tr		6.3		ns	$V_{GS} = 10 V,$
Turn-off Delay Time	$t_{d(off)}$		33.2		ns	$R_G = 0 \Omega$
Fall Time	t <sub>f</sub>		3.9		ns	
Total Gate Charge	Q <sub>G</sub>		29.8		nC	V <sub>DD</sub> = 48 V,
Gate to Source Charge	Q <sub>GS</sub>		4.2		nC	V <sub>GS</sub> = 10 V,
Gate to Drain Charge	$Q_{GD}$		9.0		nC	I <sub>D</sub> = 30 A
Body Diode Forward Voltage *1	$V_{F(S-D)}$		0.92	1.5	V	I <sub>F</sub> = 30A, V <sub>GS</sub> = 0 V
Reverse Recovery Time	t <sub>rr</sub>		30		ns	I <sub>F</sub> = 30 A, V <sub>GS</sub> = 0 V,
Reverse Recovery Charge	Qrr		39.6		nC	di/dt = 100 A/μs

Note: \*1. Pulsed

## **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

## TEST CIRCUIT 2 SWITCHING TIME





## **TEST CIRCUIT 3 GATE CHARGE**

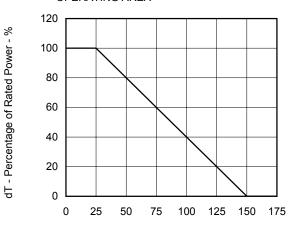
$$\begin{array}{c|c} D.U.T. \\ I_G = 2 \text{ mA} \\ \hline \end{array}$$

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90%

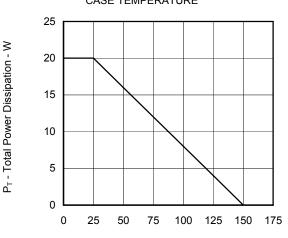
## Typical Characteristics (T<sub>A</sub> = 25°C)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



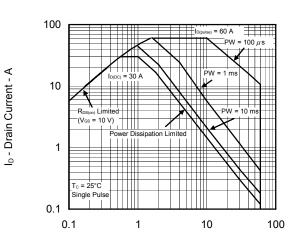
 $T_{\text{C}}$  - Case Temperature -  $^{\circ}\text{C}$ 

# TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



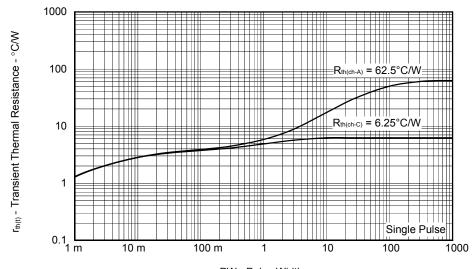
T<sub>C</sub> - Case Temperature - °C

#### FORWARD BIAS SAFE OPERATING AREA



 $V_{\text{\scriptsize DS}}$  - Drain to Source Voltage - V

#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



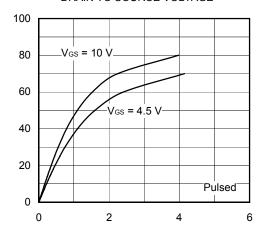
PW - Pulse Width - s

lo - Drain Current - A

V<sub>GS(off)</sub> - Gate to Source Cut-off Voltage - V

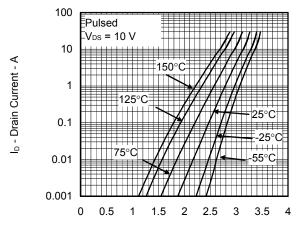
 $R_{\text{DS}(\text{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

# DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



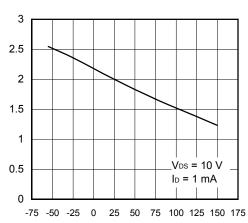
 $V_{\text{\scriptsize DS}}$  - Drain to Source Voltage - V

#### FORWARD TRANSFER CHARACTERISTICS



 $V_{\text{GS}}$  - Gate to Source Voltage - V

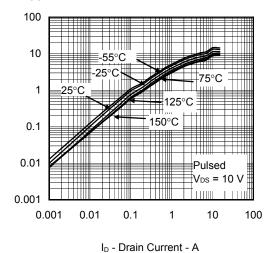
# GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

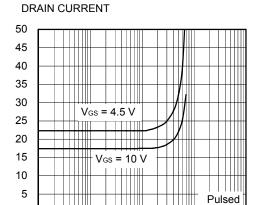


 $T_{\text{ch}}$  - Channel Temperature -  $^{\circ}\text{C}$ 

DRAIN TO SOURCE ON-STATE RESISTANCE vs.

# FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT





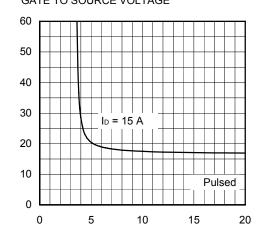
I<sub>D</sub> - Drain Current - A

100

1000

10

# DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



 $V_{\text{GS}}$  - Gate to Source Voltage - V

y<sub>fs</sub> | - Forward Transfer Admittance - S

0

0.1

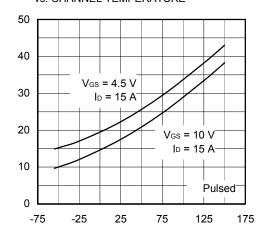


 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

td(on), tr, td(off), tr - Switching Time - ns

IF - Diode Forward Current - A

# DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



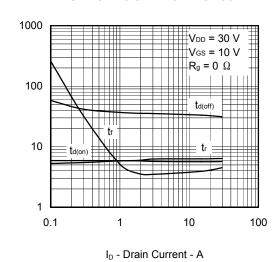
T<sub>ch</sub> - Channel Temperature - °C

# 10000 Ciss 1000 Ciss 1000 Coss 1000 Coss 1000 Coss 1000 Coss 1000 Coss 100 Coss 100

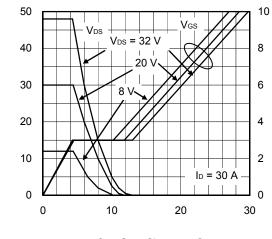
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

V<sub>DS</sub> - Drain to Source Voltage - V

#### SWITCHING CHARACTERISTICS

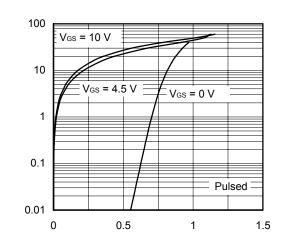


# DYNAMIC INPUT/OUTPUT CHARACTERISTICS



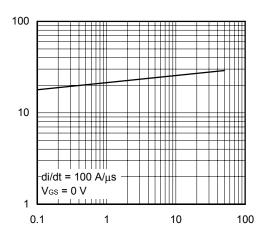
Q<sub>G</sub> - Gate Charge - nC

## SOURCE TO DRAIN DIODE FORWARD VOLTAGE



V<sub>F(S-D)</sub> - Source to Drain Voltage - V

## REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



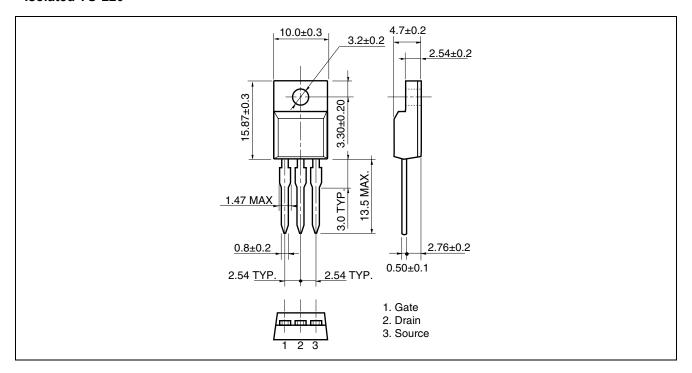
I<sub>F</sub> - Diode Forward Current - A

t<sub>rr</sub> - Reverse Recovery Time - ns

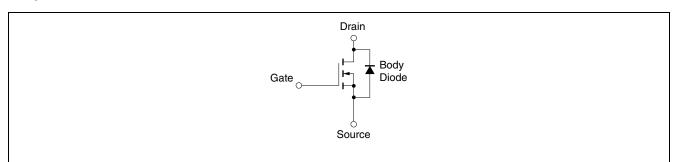
V<sub>DS</sub> - Drain to Source Voltage - V

## Package Drawings (Unit: mm)

#### **Isolated TO-220**



## **Equivalent Circuit**



Remark

Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

**Revision History** 

## N0600N Data Sheet

		Description		
Rev.	Date	Page	Summary	
1.00	Jan 25, 2011	-	First Edition Issued	

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